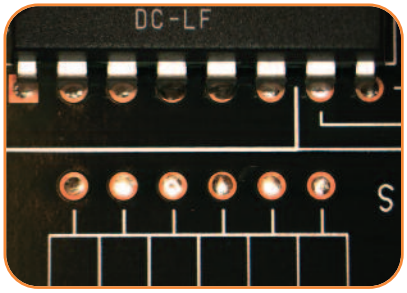
ALPHA® Vaculoy® SACX® 0807 Lead-Free Wave Solder Alloy

Get high soldering reliability and SAC305-like performance with our low-Ag alloy.

ALPHA® Vaculoy® SACX® 0807:

- High soldering reliability even on complex dual-sided PCBs
- Low surface tension creates fast wetting for excellent hole fill and low SMD-related defects
- Low Cu dissolution rate reduces erosion potential during high temperature, high exposure time processes, including rework
- Engineered for low drossing

ALPHA® SACX® 0807



Sn/Cu/Ni

alpha

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ALPHA® Vaculoy® SACX® 0807 Lead-Free Wave Solder Alloy

Get high soldering reliability and SAC305-like performance with our low-Ag alloy.

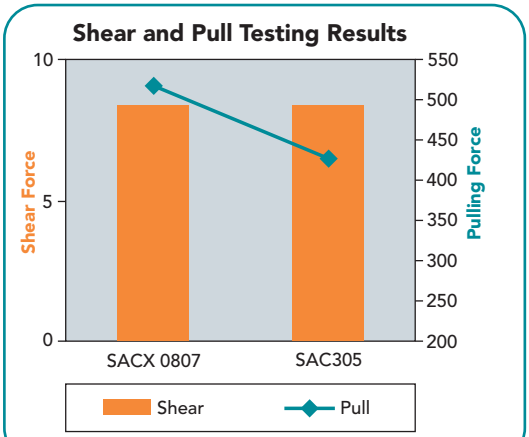
ALPHA® Vaculoy® SACX® 0807 delivers process costs saving versus SAC305.

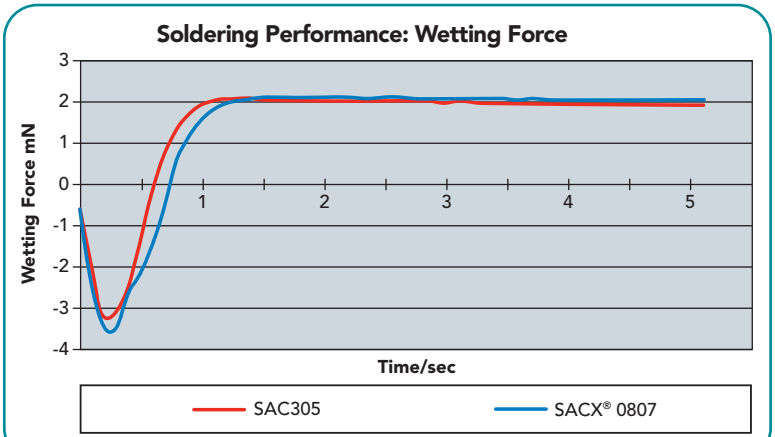
- Low-Ag content for lower material costs
- Low operating temperature requirement helps lower energy costs
- Low dross rate for higher alloy utilization and less waste

ALPHA® Vaculoy® SACX® 0807 additives contribute to high joint strength and reliability similar to SAC305.

ALPHA® Vaculoy® SACX® 0807 delivers excellent hole fill:

- Wetting performance nearly identical to SAC305
- High wetting force
- Lower surface tension results in faster wetting
- Faster wetting means better hole fill





ALPHA® SACX-0800 replenishment alloy is also available.

Performance Summary

PROCESS BENEFIT	ALPHA VACULOY SACX 0807	PERFORMANCE CAPABILITY	CUSTOMER BENEFIT
WAVE SOLDER PROCESS	Yield	Comparable yield to industry standard Vaculoy SAC305 and much superior to Sn/Cu/Ni-based alloys	Lower rework and warranty costs
	Wetting speed	Wetting speed of 0.07 sec compared to 0.06 for industry Vaculoy SAC305	High yield and throughput
	Contact time, pot temperature and conveyor speed	Contact time 2.0-5.0 sec; pot temperature 255-265°C; Conveyor speeds 0.8-1.5 m/min. (2.6-5.3 ft/min)	Wide wave solder process window
PROCESS MAINTENANCE	Dross generation	Low levels of dross generation, approx. 50% less than SACX305	Lower solder waste
	Copper dissolution rate	Lower rate of Cu dissolution compared to industry standard SAC305	Alloy monitoring costs are lower
JOINT RELIABILITY	Surface mount shear strength	Surface mount components shear strength comparable to industry standard Vaculoy SAC305	Equivalent reliability at lower cost
	Through-hole pull strength	Surface mount components pull strength comparable to industry standard Vaculoy SAC305	Equivalent reliability at lower cost
	Thermal cycling	Equivalent results compared to industry standard Vaculoy SAC305	Indication of acceptable product life

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